LCD / LCM SPECIFICATION



WINSTAR Display Co.,Ltd. 華凌光電股份有限公司



WEB: https://www.winstar.com.tw E-mail: sales@winstar.com.tw

SPECIFICATION

CUSTOMER :		
MODULE NO.:	WO12864C	2-NFG#
APPROVED BY:		
(FOR CUSTOMER USE ONLY)	PCB VERSION:	DATA:

SALES BY	APPROVED BY	CHECKED BY	PREPARED BY

VERSION	DATE	REVISED PAGE NO.	SUMMARY
G	2019/08/27		Modify Material List of Components for RoHs



DOC. FIRST ISSUE RECORDS OF REVISION **REVISED** VERSION DATE **SUMMARY** PAGE NO. 2009/12/02 First issue 0 2011/05/03 Modify V0-VSS A Remove IC information В 2014/04/25 C 2014/09/30 Add pull tape. Modify Precautions in use D 2016/01/27 of LCD Modules & Static electricity test Add FPC bending rule 2016/11/18 E Correct Interface Pin 2019/07/23 F Function. Modify Material List of G 2019/08/27

Components for RoHs

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- 1.Module Classification Information
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1. Module Classification Information

① Brand: WINSTAR DISPLAY CORPORATION

② Display Type: H→Character Type, G→Graphic Type, X→TAB Type, O→COG Type

③ Display Font: 128 * 64 dot

Model serials no.

 \bigcirc Backlight Type: N \rightarrow Without backlight T \rightarrow LED, White L \rightarrow LED, Full color

 $B\rightarrow EL$, Blue green $A\rightarrow LED$, Amber $J\rightarrow DIP$ LED, Blue $D\rightarrow EL$, Green $R\rightarrow LED$, Red $K\rightarrow DIP$ LED, White

W→EL, White O→LED, Orange E→DIP LED, Yellow Green

 $M\rightarrow$ EL, Yellow Green $G\rightarrow$ LED, Green $H\rightarrow$ DIP LED, Amber $F\rightarrow$ CCFL, White $P\rightarrow$ LED, Blue $I\rightarrow$ DIP LED, Red

 $Y\rightarrow$ LED, Yellow Green $X\rightarrow$ LED, Dual color $G\rightarrow$ LED, Green $C\rightarrow$ LED, Full color

© LCD Mode : B→TN Positive, Gray V→FSTN Negative, Blue

N→TN Negative, T→FSTN Negative, Black

L→VA Negative D→FSTN Negative (Double film)

 $H \rightarrow HTN$ Positive, Gray $F \rightarrow FSTN$ Positive $I \rightarrow HTN$ Negative, Black $K \rightarrow FSC$ Negative $U \rightarrow HTN$ Negative, Blue $S \rightarrow FSC$ Positive

M→STN Negative, Blue E→ISTN Negative, Black
G→STN Positive, Gray C→CSTN Negative, Black
Y→STN Positive, Yellow Green A→ASTN Negative, Black

② LCD Polarize A→Reflective, N.T, 6:00 H→Transflective, W.T,6:00

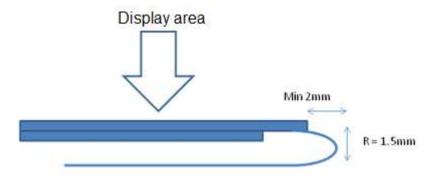
Type/ Temperature D→Reflective, N.T, 12:00 K→Transflective, W.T,12:00 range/ View G→Reflective, W. T, 6:00 C→Transmissive, N.T,6:00 direction J→Reflective, W. T, 12:00 F→Transmissive, N.T,12:00

B→Transflective, N.T,6:00 I→Transmissive, W. T, 6:00 E→Transflective, N.T.12:00 L→Transmissive, W.T,12:00

Special Code #: Fit in with the ROHS Directions and regulations

2. Precautions in use of LCD Modules

- (1) Avoid applying excessive shocks to the module or making any alterations or modifications to it.
- (2)Don't make extra holes on the printed circuit board, modify its shape or change the components of LCD module.
- (3)Don't disassemble the LCM.
- (4)Don't operate it above the absolute maximum rating.
- (5)Don't drop, bend or twist LCM.
- (6) Soldering: only to the I/O terminals.
- (7)Storage: please storage in anti-static electricity container and clean environment.
- (8) Winstar have the right to change the passive components, including R3,R6 & backlight adjust resistors. (Resistors, capacitors and other passive components will have different appearance and color caused by the different supplier.)
- (9) Winstar have the right to change the PCB Rev. (In order to satisfy the supplying stability, management optimization and the best product performance...etc, under the premise of not affecting the electrical characteristics and external dimensions, Winstar have the right to modify the version.)
- (10) To ensure the stability of the display screen, please apply screen saver after showing 30 mins of fixed display content.
- (11) The limitation of FPC bending



3.General Specification

Item	Dimension	Unit			
Number of Characters	128 x 64 dots	_			
Module dimension	53.2 x 37.8 x 2.0(MAX)	mm			
View area	45.2 x 27.0	mm			
Active area	40.92 x 24.28	mm			
Dot size	0.28 x 0.34	mm			
Dot pitch	0.32 x 0.38	mm			
LCD type	FSTN Positive Reflective (In LCD production, It will occur slightly color difference. We can only guarantee the same color in the same batch.)				
Duty	1/64 , 1/9 Bias				
View direction	6 o'clock				
Backlight Type	Without backlight				
IC	ST7565P				

4.Absolute Maximum Ratings

Item	Symbol	Min	Тур	Max	Unit
Operating Temperature	T_{OP}	-20	_	+70	$^{\circ}\!\mathbb{C}$
Storage Temperature	T_{ST}	-30	_	+80	$^{\circ}\!\mathbb{C}$
Power Supply Voltage	VDD	-0.3	_	3.6	V
Power supply voltage (VDD standard)	V0, VOUT	-0.3	_	14.5	V
Power supply voltage (VDD standard)	V1, V2, V3, V4	-0.3	_	V0+0.3	V

5.Electrical Characteristics

Item	Symbol	Condition	Min	Тур	Max	Unit
Supply Voltage For Logic	V_{DD} - V_{SS}	_	2.7	3.0	3.3	V
		Ta=-20°C	_	_	_	V
Supply Voltage For LCM	VOP	Ta=25°℃	9.4	9.6	9.8	V
		Ta=70°C	_	_	_	V
Input High Volt.	V_{IH}	_	$0.8~\mathrm{V_{DD}}$	_	V_{DD}	V
Input Low Volt.	V_{IL}	_	Vss	_	$0.2~\mathrm{V_{DD}}$	V
Output High Volt.	V_{OH}	_	$0.8~\mathrm{V_{DD}}$	_	V_{DD}	V
Output Low Volt.	V_{OL}	_	Vss	_	$0.2V_{DD}$	V
Supply Current(No include	т	V 20V		0.40	1.0	A
LED Backlight)	I_{DD}	$V_{DD}=3.0V$	_	0.49	1.0	mA

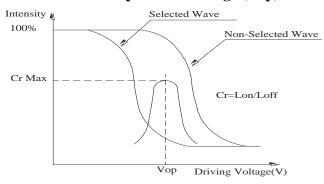
NOTE 1: Please kindly consider to design the Vop to be adjustable while programing the software to match LCD contrast tolerance

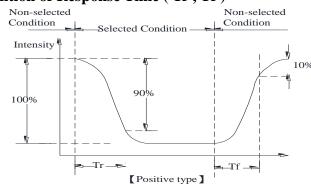
6.Optical Characteristics

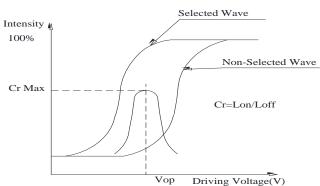
Item	Symbol	Condition	Min	Тур	Max	Unit
	θ	CR≧2	0	_	30	$\Psi = 180^{\circ}$
X7: A1 -	θ	CR≧2	0	_	60	$\Psi = 0^{\circ}$
View Angle	θ	CR≧2	0	_	45	$\Psi = 90^{\circ}$
	θ	CR≧2	0	_	45	$\Psi = 270^{\circ}$
Contrast Ratio	CR	_	_	5	_	_
D	T rise	_	_	200	300	ms
Response Time	T fall	_	_	250	350	ms

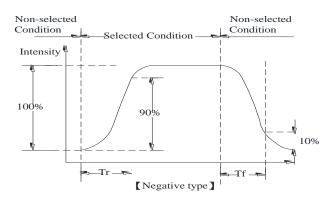
Definition of Operation Voltage (Vop)

Definition of Response Time (Tr, Tf)









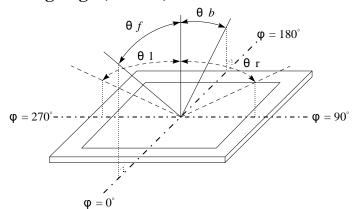
Conditions:

Operating Voltage: Vop

Viewing Angle(θ , φ): 0° , 0°

Frame Frequency : 64 HZ $\;\;$ Driving Waveform : 1/N duty , 1/a bias

Definition of viewing angle $(CR \ge 2)$

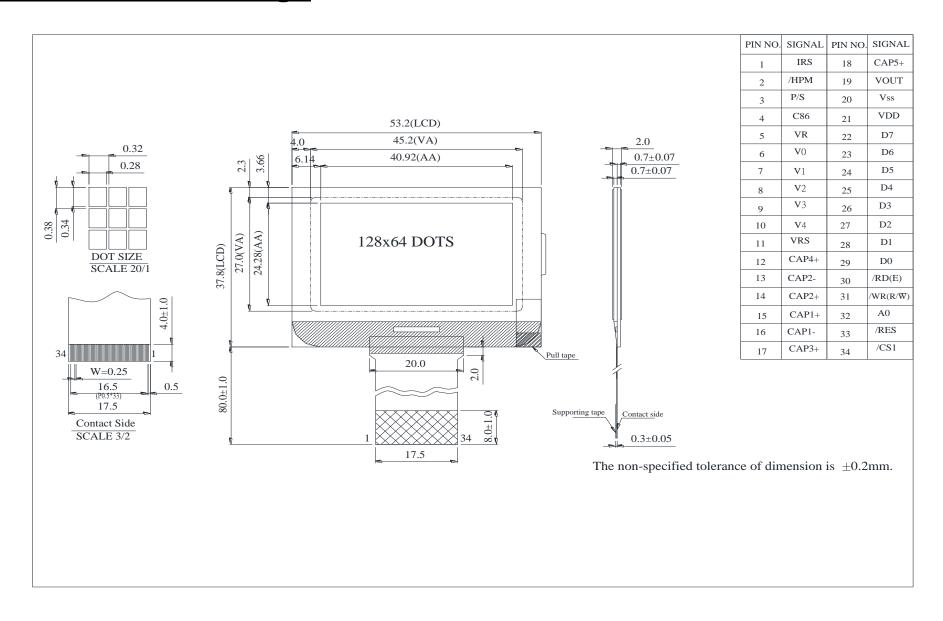


7.Interface Pin Function

Pin No.	Symbol	Level			Desc	cription				
			This term	This terminal selects the resistors for the V0 voltage level adjustment.						
			IRS = "H	I": Use the inter	nal resistor	rs.				
1	IRS	I	IRS = "I	": Do not use th	ne internal i	resistors. Th	ne V0 voltag	e level is		
			regulated	l by an external	resistive vo	oltage divid	er attached t	o the VR		
			terminal	erminal						
				This is the power control terminal for the power supply circuit for liquid						
2	/HPM	I	•	rystal drive.						
				"H": Normal m						
				"L": High powe						
				This is the parallel data input/serial data input switch terminal.						
				": Parallel data	•					
				": Serial data in	•	- 41- a D/C a4a	.4			
			The folio	owing applies de	epending of	i the P/S sta	itus:			
	D (0		P/S	Data/Command	Data	Read/Write	Serial Clock			
3	P/S	I	"H"	A0	D0 to D7	/RD, /WR	Х			
			"L"	A0	SI (D7)	Write only	SCL (D6)			
			When P/	S = "L", D0 to I	D5 fixed	"H".	•			
			/RD (E)	and /WR (R/W)	are fixed t	o either "H'	' or "L".			
			With ser	al data input, It	is impossil	ble read dat	a from RAM			
4			This is th	ne MPU interfac	e selection	pin.				
4	C86	I		H": 6800 Series						
				L": 8080 Series						
			1	oltage regulator			voltage bet	ween VSS and		
5	VR	I	V0 through a resistive voltage divider. IRS = "L": the V0 voltage regulator internal resistors are not used.							
		Power	IKS – F	I": the V0 volta	ige regulaid	or internal re	esistors are t	ised.		
6~10	V0~V4	Supply	This is a	This is a multi-level power supply for the liquid crystal drive.						
11	VRS	Power	This is the internal-output VREG power supply for the LCD power							
11	VKS	Supply	supply v	supply voltage regulator.						
12	CAP4+	О	DC/DC	DC/DC voltage converter.						
12	CAD2	0	DC/DC v	voltage converte	er. Connect	a capacitor	between thi	s terminal and		
13	CAP2-	О	the CAP	2P terminal.						

14	CAP2+	О	DC/DC voltage converter. Connect a capacitor between this terminal and the CAP2N terminal.
15	CAP1+	О	DC/DC voltage converter. Connect a capacitor between this terminal and
13	CHIT	O	the CAP1N terminal.
16 CAP1- O		O	DC/DC voltage converter. Connect a capacitor between this terminal and
	_	_	the CAP1P terminal.
17	CAP3+	О	DC/DC voltage converter. Connect a capacitor between this terminal and
			the CAP1N terminal.
18	CAP5+	О	DC/DC voltage converter.
19	VOUT	О	DC/DC voltage converter. Connect a capacitor between this terminal and
			vss or VDD
20	VSS	Power Supply	Ground
21	VDD	Power	Power supply
		Supply	
22~29	D7~D0	I/O	Data bus line
			• When connected to 8080 series MPU, this pin is treated as the "/RD"
	/RD(E)	,	signal of the 8080 MPU and is LOW-active.
30			The data bus is in an output status when this signal is "L".
30		I	• When connected to 6800 series MPU, this pin is treated as the "E"
			signal of the 6800 MPU and is HIGH-active.
			This is the enable clock input terminal of the 6800 Series MPU.
			• When connected to 8080 series MPU, this pin is treated as the "/WR"
			signal of the 8080 MPU and is LOW-active.
			The signals on the data bus are latched at the rising edge of the /WR
31	/WR(R/W)	I	signal.
	/ W K(K/ W)	1	• When connected to 6800 series MPU, this pin is treated as the "R/W"
			signal of the 6800 MPU and decides the access type:
			When R/W = "H": Read.
			When R/W = "L": Write.
			This is connect to the least significant bit of the normal MPU address bus,
32	A0	I	and it determines whether the data bits are data or command.
	730		A0 = ``H'': Indicates that D0 to D7 are display data.
			A0 = "L": Indicates that D0 to D7 are control data.
33	/RES	I	When RES is set to "L", the setting are initialized.
34	/CS1	I	This is the chip select signal.

8.Contour Drawing



9.Reliability

Content of Reliability Test (Wide temperature, -20°c~70°C)

	Environmental Test							
Test Item	Content of Test	Test Condition	Not e					
High Temperature storage	Endurance test applying the high storage temperature for a long time.	80°C 200hrs	2					
Low Temperature storage	Endurance test applying the low storage temperature for a long time.	-30°C 200hrs	1,2					
High Temperature Operation	Endurance test applying the electric stress (Voltage & Current) and the thermal stress to the element for a long time.	70°C 200hrs						
Low Temperature Operation	Endurance test applying the electric stress under low temperature for a long time.	-20°C 200hrs	1					
High Temperature/ Humidity storage	The module should be allowed to stand at 60 °C,90%RH max For 96hrs under no-load condition excluding the polarizer, Then taking it out and drying it at normal temperature.	60°C,90%RH 96hrs	1,2					
Thermal shock resistance	The sample should be allowed stand the following 10 cycles of operation -20°C 25°C 70°C 30min 5min 30min 1 cycle	-20°C/70°C 10 cycles	_					
Vibration test	Endurance test applying the vibration during transportation and using.	Total fixed amplitude: 1.5mm Vibration Frequency: 10~55Hz One cycle 60 seconds to 3 directions of X,Y,Z for Each 15 minutes	3					
Static electricity test	Endurance test applying the electric stress to the terminal.	VS=±600V(contact), ±800v(air), RS=330Ω CS=150pF 10 times						

Note1: No dew condensation to be observed.

Note2: The function test shall be conducted after 4 hours storage at the normal

Temperature and humidity after remove from the test chamber.

Note3: The packing have to including into the vibration testing.

10.Inspection specification

NO	Item	Criterion				AQL
01	Electrical Testing	Missing vertical, horizontal segment, segment contrast defect. Missing character, dot or icon. Display malfunction. No function or no display. Current consumption exceeds product specifications. LCD viewing angle defect. Mixed product types. Contrast defect.				
02	Black or white spots on LCD (display only)	 2.1 White and black spots on display ≤0.25mm, no more than three white or black spots present. 2.2 Densely spaced: No more than two spots or lines within 3mm 				2.5
03	LCD black spots, white spots, contamination (non-display)	3.1 Round type $\Phi=(x+y)/2$ X 3.2 Line type : (↓ ▼ Y	SIZE $\Phi \le 0.10$ $0.10 < \Phi \le 0.20$ $0.20 < \Phi \le 0.25$ $0.25 < \Phi$	Acceptable Q TY Accept no dense 2 1 0 Acceptable Q TY Acceptable Q TY Accept no dense 2 As round type	2.5
04	Polarizer bubbles	If bubbles are vijudge using black specifications, in to find, must characteristic specify direction	ck spot not easy eck in	Size Φ $\Phi \le 0.20$ $0.20 < \Phi \le 0.50$ $0.50 < \Phi \le 1.00$ $1.00 < \Phi$ Total Q TY	Acceptable Q TY Accept no dense 3 2 0 3	2.5

NO	Item	Criterion			AQL		
05	Scratches	Follow NO.3 LCD black spots, white spots, contamination					
			Glass thickness a: LC	ip thickness CD side length			
		6.1 General glass chip: 6.1.1 Chip on panel surface an		panels:			
		z: Chip thickness	y: Chip width	x: Chip length			
06	Chipped	Z≦1/2t	Not over viewing area	x ≤ 1/8a	2.5		
00	glass	$1/2t < z \leq 2t$	Not exceed 1/3k	x ≤ 1/8a	2.3		
			y: Chip width Not over viewing area	x: Chip length x≤1/8a			
		$1/2t < z \le 2t$	Not exceed 1/3k	x ≤ 1/8a			
		⊙ If there are 2 or more	e chips, x is the total len	gth of each chip.			

NO	Item	Criterion						
		x: Chip length y: Chip width z: Chip thickness k: Seal width t: Glass thickness a: LCD side length L: Electrode pad length 6.2 Protrusion over terminal: 6.2.1 Chip on electrode pad:						
			Chip length	z: Chip thickness				
		$ \begin{array}{ c c c c c }\hline y \leq 0.5 \text{mm} & x \leq 1/8a & 0 < z \leq t \\ \hline 6.2.2 \text{ Non-conductive portion:} \end{array} $						
06	Glass	y Z Z Z Z Z Z Z Z Z Z Z Z Z Z Z Z Z Z Z						
		y: Chip width	x: Chip length	z: Chip thickness				
		y≦ L	x≤1/8a	$0 < z \leq t$				
		 ⊙ If the chipped area touches the ITO terminal, over 2/3 of the ITO must remain and be inspected according to electrode terminal specifications. ⊙ If the product will be heat sealed by the customer, the alignment mark not be damaged. 6.2.3 Substrate protuberance and internal crack. y: width $x: \text{length}$ y ≤ 1/3L $x \le a$ 						

NO	Item	Criterion		
07	Cracked glass	The LCD with extensive crack is not acceptable.		
08	Backlight elements	8.1 Illumination source flickers when lit.8.2 Spots or scratched that appear when lit must be judged.Using LCD spot, lines and contamination standards.		
09 Bezel		 8.3 Backlight doesn't light or color wrong. 9.1 Bezel may not have rust, be deformed or have fingerprints, stains or other contamination. 9.2 Bezel must comply with job specifications. 		
10	stains of other contamination. 9.2 Bezel must comply with job specifications. 10.1 COB seal may not have pinholes larger than 0.2mm or contamination. 10.2 COB seal surface may not have pinholes through to the IC. 10.3 The height of the COB should not exceed the height indicated in the assembly diagram. 10.4 There may not be more than 2mm of sealant outside the seal area on the PCB. And there should be no more than three places. 10.5 No oxidation or contamination PCB terminals. 10.6 Parts on PCB must be the same as on the production characteristic chart. There should be no wrong parts, missing parts or excess parts. 10.7 The jumper on the PCB should conform to the product characteristic chart. 10.8 If solder gets on bezel tab pads, LED pad, zebra pad or screw hold pad, make sure it is smoothed down. 10.9 The Scraping testing standard for Copper Coating of PCB		0.65 2.5 2.5 0.65 2.5 0.65 2.5 2.5 2.5 2.5 2.5 2.5 2.5	
11	Soldering	11.1 No un-melted solder paste may be present on the PCB. 11.2 No cold solder joints, missing solder connections, oxidation or icicle. 11.3 No residue or solder balls on PCB. 11.4 No short circuits in components on PCB.	2.5 2.5 2.5 0.65	

NO	Item	Criterion	AQL
		12.1 No oxidation, contamination, curves or, bends on interface	2.5
		Pin (OLB) of TCP.	
		12.2 No cracks on interface pin (OLB) of TCP.	0.65
		12.3 No contamination, solder residue or solder balls on product.	2.5
		12.4 The IC on the TCP may not be damaged, circuits.	2.5
		12.5 The uppermost edge of the protective strip on the interface	2.5
		pin must be present or look as if it cause the interface pin to sever.	
	General	12.6 The residual rosin or tin oil of soldering (component or chip	2.5
12		component) is not burned into brown or black color.	
	appearance	12.7 Sealant on top of the ITO circuit has not hardened.	2.5
		12.8 Pin type must match type in specification sheet.	0.65
		12.9 LCD pin loose or missing pins.	0.65
		12.10 Product packaging must the same as specified on packaging	0.65
		specification sheet.	
		12.11 Product dimension and structure must conform to product	0.65
		specification sheet.	
		12.12 Visual defect outside of VA is not considered to be rejection.	0.65

11.Material List of Components for

RoHs

1. WINSTAR Display Co., Ltd hereby declares that all of or part of products (with the mark "#"in code), including, but not limited to, the LCM, accessories or packages, manufactured and/or delivered to your company (including your subsidiaries and affiliated company) directly or indirectly by our company (including our subsidiaries or affiliated companies) do not intentionally contain any of the substances listed in all applicable EU directives and regulations, including the following substances.

Exhibit A: The Harmful Material List

Material	Cd	Pb	Hg	Cr6+	PBB	PBDE	DEHP	BBP	DBP	DIBP
Limited	100	1000	1000	1000	1000	1000	1000	1000	1000	1000
Value	ppm	ppm	ppm	ppm	ppm	ppm	ppm	ppm	ppm	ppm
Above limited value is set up according to RoHS.										

2.Process for RoHS requirement : (only for RoHS inspection)

(1) Use the Sn/Ag/Cu soldering surface; the surface of Pb-free solder is rougher than we used before.

(2) Heat-resistance temp. :

Reflow: 250° C, 30 seconds Max.;

Connector soldering wave or hand soldering : 320°C, 10 seconds max.

(3) Temp. curve of reflow, max. Temp. $: 235\pm5^{\circ}C$;

Recommended customer's soldering temp. of connector: 280°C, 3 seconds.

12.Recommendable Storage

- 1. Place the panel or module in the temperature 25°C±5°C and the humidity below 65% RH
- 2. Do not place the module near organics solvents or corrosive gases.
- 3. Do not crush, shake, or jolt the module.

		te Feedback Sheet	
dule Number: l 、 Panel Specification:		Page: 1	
1. Panel Type:	Pass	□ NG ,	
2. View Direction:	☐ Pass	□ NG ,	
3. Numbers of Dots:	☐ Pass	□ NG ,	
4. View Area:	Pass	□ NG ,	
5. Active Area:	☐ Pass	□ NG ,	
6. Operating Temperature:	☐ Pass	□ NG ,	
7. Storage Temperature:	Pass	□ NG ,	
8. Others:			
• Mechanical Specification :			
1. PCB Size:	☐ Pass	□ NG,	
2. Frame Size:	Pass	□ NG ,	
3. Materal of Frame:	Pass	□ NG ,	
4. Connector Position:	☐ Pass	□ NG ,	
5. Fix Hole Position:	☐ Pass	□ NG ,	
6. Backlight Position:	☐ Pass	□ NG ,	
7. Thickness of PCB:	Pass	□ NG ,	
8. Height of Frame to PCB:	Pass	□ NG ,	
9. Height of Module:	Pass	☐ NG ,	
10. Others:	Pass	□ NG ,	
Relative Hole Size:			
1. Pitch of Connector:	Pass	□ NG ,	
2. Hole size of Connector:	Pass	□ NG ,	
3. Mounting Hole size:	Pass	□ NG ,	
4. Mounting Hole Type:	☐ Pass	□ NG ,	
5. Others:	☐ Pass	□ NG ,	
• Backlight Specification :			
1. B/L Type:	☐ Pass	☐ NG ,	
2. B/L Color:	Pass	☐ NG ,	
3. B/L Driving Voltage (Refere	nce for LEI	O Type): Pass NG,	
4. B/L Driving Current:	Pass	□ NG ,	
5. Brightness of B/L:	Pass	□ NG ,	
6. B/L Solder Method:	Pass	□ NG ,	
7. Others:	Pass	□ NG ,	



	winstar					
Modu	lle Number:		Page: 2			
5、	Electronic Characteristics of	Module:				
1.	Input Voltage:	Pass	☐ NG ,			
2.	Supply Current:	Pass	☐ NG ,			
3.	Driving Voltage for LCD:	☐ Pass	☐ NG ,			
4.	Contrast for LCD:	Pass	☐ NG ,			
5.	B/L Driving Method:	Pass	□ NG ,			
6.	Negative Voltage Output:	Pass	□ NG ,			
7.	Interface Function:	Pass	□ NG ,			
8.	LCD Uniformity:	Pass	□ NG ,			
9.	ESD test:	Pass	□ NG ,			
10.	Others:	Pass	□ NG ,			
6、	Summary :					
	Sales signature :					
	Customer Signature:		Date : / /			